

Title (en)

MULTI-LAYER PRINTED CIRCUIT BOARD HAVING A PRINTED COIL AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

MULTILAYER-PLATINE MIT GEDRUCKTER SPULE UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

CARTE DE CIRCUITS IMPRIMÉS MULTICOUCHE À BOBINES IMPRIMÉES ET PROCÉDÉ DE FABRICATION DE LADITE CARTE

Publication

**EP 3375261 A1 20180919 (DE)**

Application

**EP 16810237 A 20161109**

Priority

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Abstract (en)

[origin: WO2017080554A1] The invention relates to a multi-layer printed circuit board, comprising vertically superimposed flat coils (1-6) which are electrically connected in series or in parallel to form a first solenoid coil (20). In order to improve the heat dissipation of the multi-layer printed circuit board, it is proposed that in each case two vertically adjacent flat coils (1,2) are arranged laterally offset relative to each other in such a manner that conductor track sections (26) of one flat coil (2) are arranged vertically in a partial overlap with two conductor track sections (7) of the other flat coil (1) in a cross section (8) perpendicular to the surface of the multi-layer printed circuit board.

IPC 8 full level

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CPC (source: CN EP US)

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Citation (search report)

See references of WO 2017080554A1

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